D2684, DECEMBER 1982—REVISED JUNE 1989

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the Preset or clear inputs sets or resets the outputs regardless of the levels of the other inputs. When Preset and Clear are inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and \overline{K} inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding \overline{K} and tying J high. They also can perform as D-type flip-flops if J and \overline{K} are tied together.

The SN54HC109 is characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 $^{\circ}\text{C}$. The SN74HC109 is characterized for operation from $-40\,^{\circ}\text{C}$ to 85 $^{\circ}\text{C}$.

FUNCTION TABLE

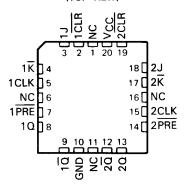
	OUTI	PUTS				
PRE	CLR	CLK	J	K	Q	ā
L	Н	Х	X	Х	Н	L
Н	L	X	Χ	Х	L	н
L	L	X	Х	Х	H‡	H‡
Н	Н	†	L	L	L	Н
н	Н	1	Н	L	TOGGLE	
н	Н	1	L	н	σ_0	\overline{a}_0
н	Н	†	Н	н	Н	L
Н	Н	L	Х	Х	a_0	$\overline{\alpha}_0$

[‡]This configuration is nonstable; that is, it will not persist when Preset or Clear return to their inactive (high) level.

SN54HC109 . . . J PACKAGE SN74HC109 . . . D OR N PACKAGE (TOP VIEW)

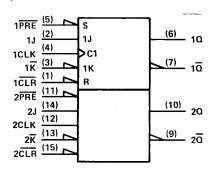
1CLR	1	U 16	Dvcc
1J 🛚	2	15]2CLR
1 ₹ 🛚	3	14] 2J
1CLK	4	13]2K
1PRE	5	12	2CLK
10 🏻	6	11	2PRE
10 🗆	7	10]2Q
GND 🗌	8	9]2 <u>Q</u>

SN54HC109 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

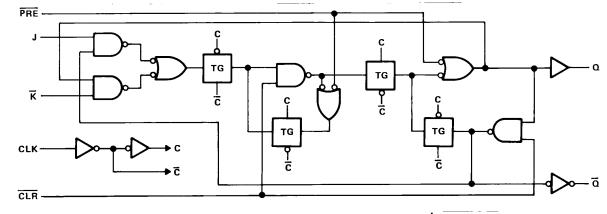
logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range†

Supply voltage, VCC
Input clamp current, $I_{ K }$ ($V_1 < 0$ or $V_1 > V_{CC}$) ± 20 mA
Output clamp current, IOK (VO < 0 or VO > VCC ±20 mA
Continuous output current, IO (VO = 0 to VCC) ±25 mA
Continuous current through VCC or GND pins
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or J package 300 °C
Lead temperature 1,6 mm (1/16 in) from case for 10 s: D or N package 260 °C
Storage temperature range65°C to 150°C
• •

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	-		SI	N54HC1	109 SN74HC109		09	UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	ONIT
Vcc	Supply voltage		2	5	6	2	5_	6	>
		V _{CC} = 2 V	1.5	_		1.5		ļ	
VIH	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
•••	-	$V_{CC} = 6 V$	4.2			4.2			
		V _{CC} = 2 V	0	,	0.3	0		0.3	
VII	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$	0		0.9	0		0.9	V
.,		$V_{CC} = 6 V$	0		1.2	0		1.2	
Vı	Input voltage	<u> </u>	0		Vcc	0		Vcc	٧
٧o	Output voltage	<u></u>	0		Vcc	0		Vcc	>
		V _{CC} = 2 V	0		1000	0		1000	
t _t	Input transition (rise and fall) times	V _{CC} = 4.5 V	0		500	0		500	ns
*C . **/*		V _{CC} = 6 V	0		400	0		400	
TA	Operating free-air temperature		-55		125	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS	Vaa	T _A = 25°C			SN54HC109		SN74HC109		UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	ONII
		2 V	1.9	1.998		1.9		1.9		
	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
V _{OH}		6 V	5.9	5.999		5.9		5.9		V
	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -4$ mA	4.5 V	3.98	4.30		3.7		3.84		
	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -5.2$ mA	6 V	5.48	5.80		5.2		5.34		
		2 V		0.002	0.1		0.1		0.1	
	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
V _{OL}		6 V		0.001	0.1		0.1]	0.1	V
	VI = VIH or VIL, IOL = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
	VI = VIH or VIL, IOL = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
l _l	VI = VCC or 0	6 V		± 0.1	± 100		± 1000	±	1000	nA
¹ cc	$V_I = V_{CC} \text{ or } 0, I_O = 0$	6 V			4		80		40	μA
C ₁		2 to 6 V		3	10		10		10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			.,	T _A = 25°C		SN54HC109		SN74HC109		UNIT
	ph. 1		vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	0	6	0	4.2	0	5	
f _{clock} Clock frequency			4.5 V	0	31	0	21	0	25	MHz
			6 V	0	36	0	25	0	29	
			2 V	100		150		125		
t _w Pulse duration	PRE or CLR low	4.5 V	20		30		25			
			6 V	17		25		21		
	Pulse duration	CLK high or low	2 V	80		120		100		ns
			4.5 V	16		24		20		
			6 V	14		20		17		
			2 V	100		150	-	125		
		Data (J, K)	4.5 V	20		30		25		
Setup time ^t su before CLK1	Setup time		6 V	17		25		21		
	before CLK1	PRE or CLR inactive	2 V	25	-	40	•	30		ns
			4.5 V	5		8		6		
			6 V	4		7		5		
			2 V	0		0		0		
th	Hold time, data after CLK1		4.5 V	0		0		0		ns
••				0		0		0		l

switching characteristics over recommended operating free-air temperature range (unless otherwise noted), $C_L = 50 pF$ (see Note 1)

PARAMETER	FROM	то	T _A = 25°C		°C	SN54I	HC109	SN74HC109			
PANAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	10		4.2		5		
f _{max}			4.5 V	31	50		21.		25		MHz
			6 V	36	60		25		29		
·			2 V		60	230		345		290	
t _{pd}	PRE or CLR	Q or $\overline{\mathbf{Q}}$	4.5 V		15	46		69		58	ns
			6 V		12	39		59		49	
			2 V		50	175		250		220	
^t pd	CLK	Q or Q	4.5 V		15	35		50		44	ns
			6 V		12	30		42		37	
			2 V		28	75		110		95	
t _t		Q or Q	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

	C _{pd}	Power dissipation capacitance per flip-flop	No load, T _A = 25 °C	35 pF typ
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NOTE 1: Load circuit and voltage waveforms are shown in Section 1.

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